

**WHAT IS CLAIMED IS:**

1. Chemical mechanical polishing (CMP) equipment for use in planarizing a semiconductor wafer, said equipment comprising : a turntable, a polishing pad disposed atop said turntable; a slurry supply unit that dispenses slurry onto an upper surface of the polishing pad; a head polishing unit having a polishing head positionable over the upper surface of the polishing pad, said polishing head being rotatable to rotate a wafer atop said polishing pad; a conditioning unit having a pad conditioning head that is movable into contact with said polishing pad and has a serrated surface that conditions said polishing pad when in contact with the pad; and a cleaning solution supply unit through which a cleaning solution is supplied, said cleaning solution supply unit having at least one spray nozzle oriented to spray the cleaning solution over a region encompassing at least a portion of the upper surface of said polishing pad.

2. The CMP equipment of claim 1, wherein said cleaning solution supply unit includes a cleaning solution supply line, said spray nozzle being disposed at an end of the cleaning solution supply line, and a flow regulator disposed in-line with said cleaning solution supply line so as to control the pressure of the cleaning solution flowing from said spray nozzle.

3. The CMP equipment of claim 1, wherein said region encompasses the

entire upper surface of said polishing pad.

4. The CMP equipment of claim 1, wherein said region also encompasses at least one of said polishing head and said pad conditioning head.

5. The CMP equipment of claim 2, wherein said region also encompasses at least one of said polishing head and said pad conditioning head.